

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jimarez et al.

Art Unit:

Serial No.:

Dkt. No.: END919980110US4

Filed:

Examiner:

Title: **FLIP CHIP C4 EXTENSION STRUCTURE AND PROCESS**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Preliminary Amendment

Sir:

Kindly enter this amendment prior to initial examination

In the Specification:

Page 1, between lines 1 and 2, insert: --This application is a divisional of Serial No. 09/782,471; filed on 2/12/2001.--

The paragraph beginning on page 35, line 7 is amended as follows:

FIGS. 23-28 illustrate process steps associated with a fourth embodiment of the present invention. FIG. 23 shows the first structure **10** of FIG. 1 such that the coat of material **18** of FIG. 1 is replaced by the volume of material **19** of FIG. 23. The volume of material **19** of FIG. 23 may include any material (e.g., a nonsolderable and nonconductive material such as a polyimide or a photosensitive resin) that could be included in the coat of material **18** of FIG. 1, or additionally epoxy adhesive or silicone adhesive. The first substrate **12** (e.g., chip, module), first conductive bodies **14** (e.g., solder bump such as C4 solder ball), and pads **16** in FIG. 23 are the same as in